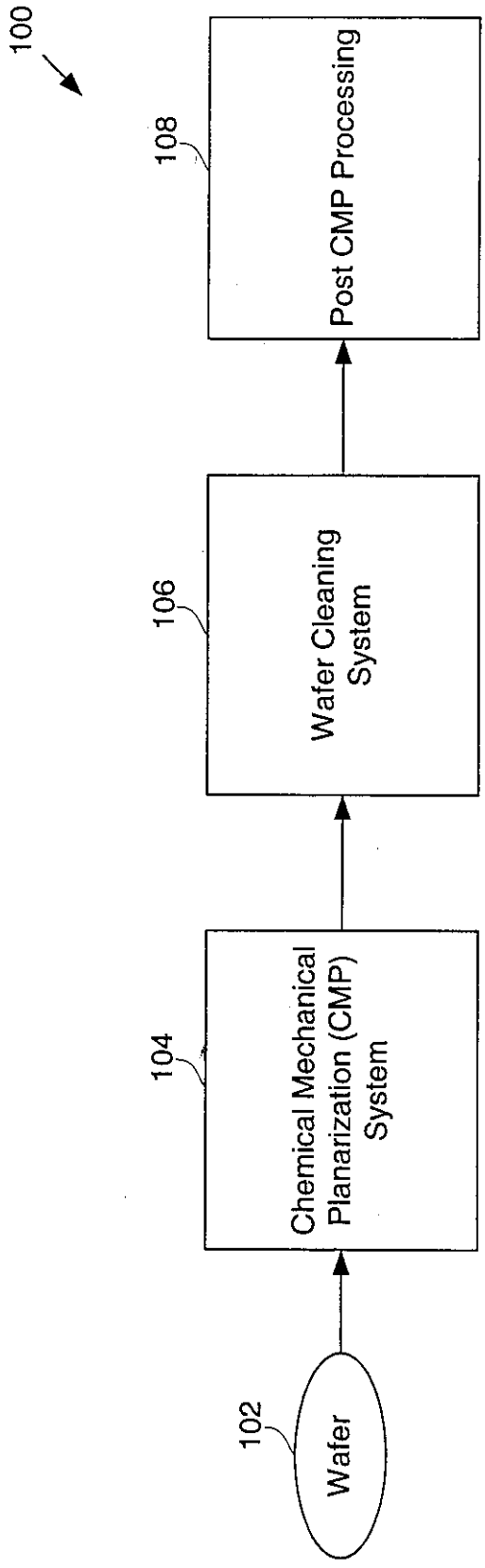

100
108
Post CMP Processing
106
Wafer Cleaning System
104
Chemical Mechanical Planarization (CMP) System
102
Wafer

FIG. 1

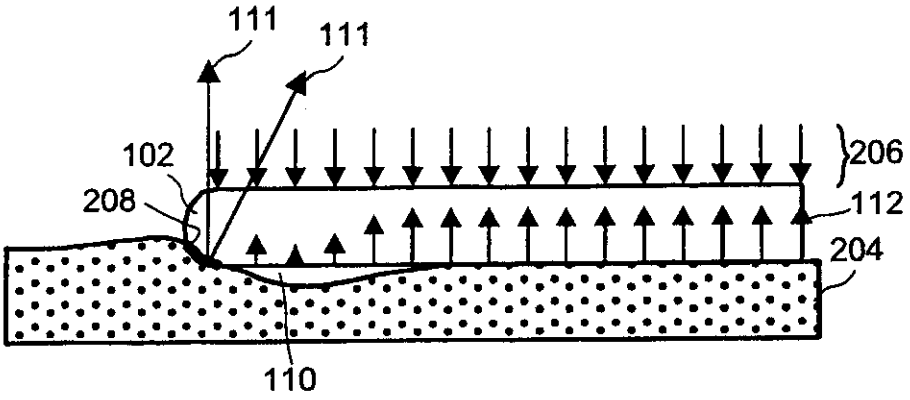



FIG. 2A

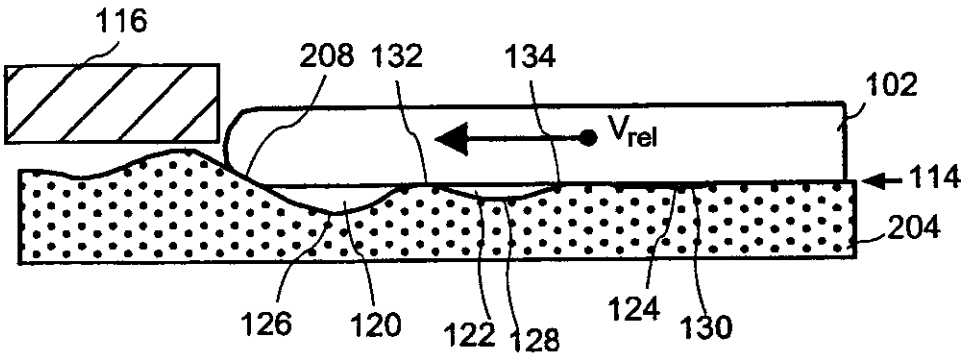



FIG. 2B

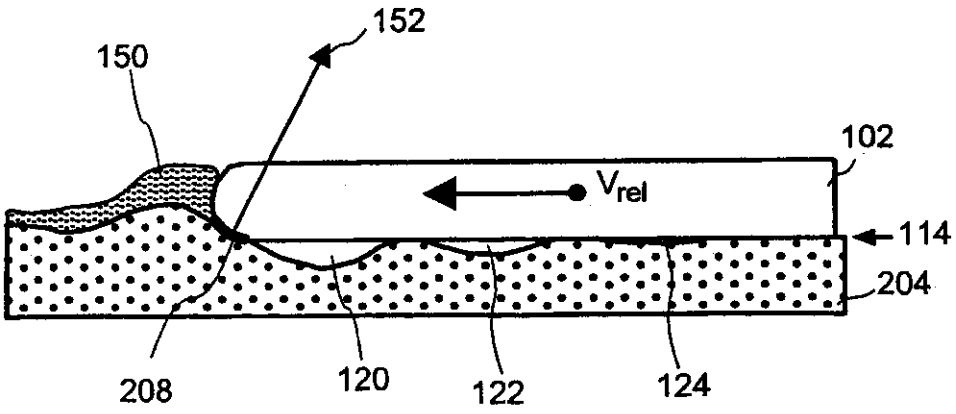



FIG. 2C

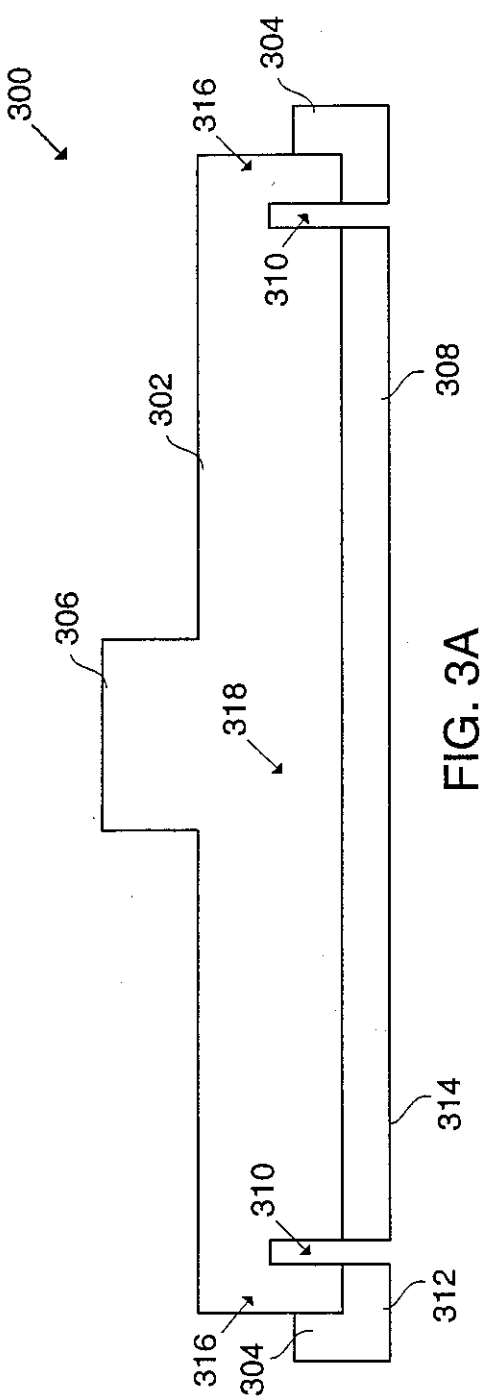

300
316
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FIG. 3A

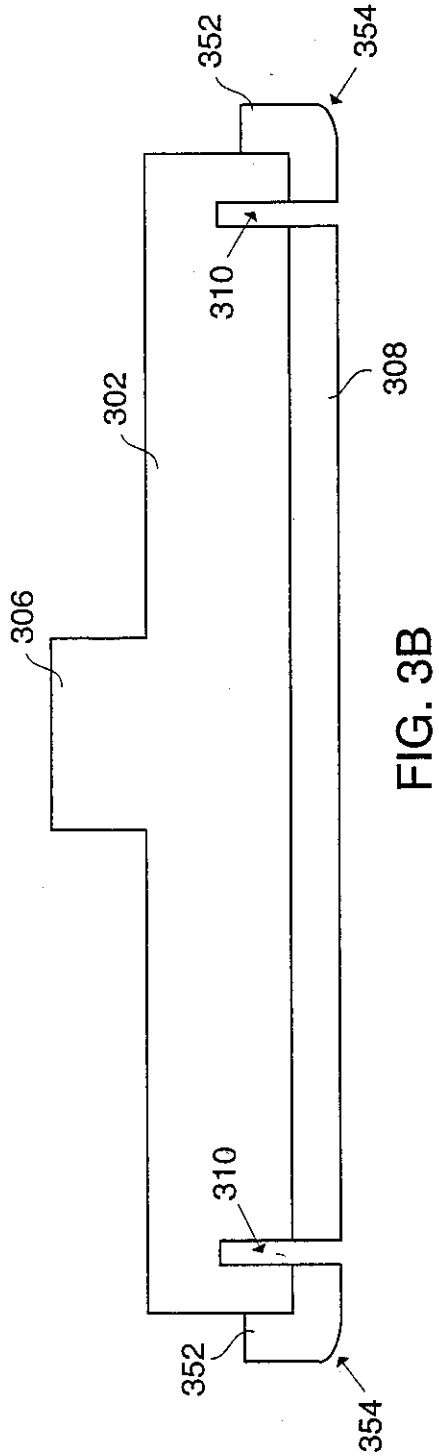

352
354
310
308
302
306
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352
354

FIG. 3B

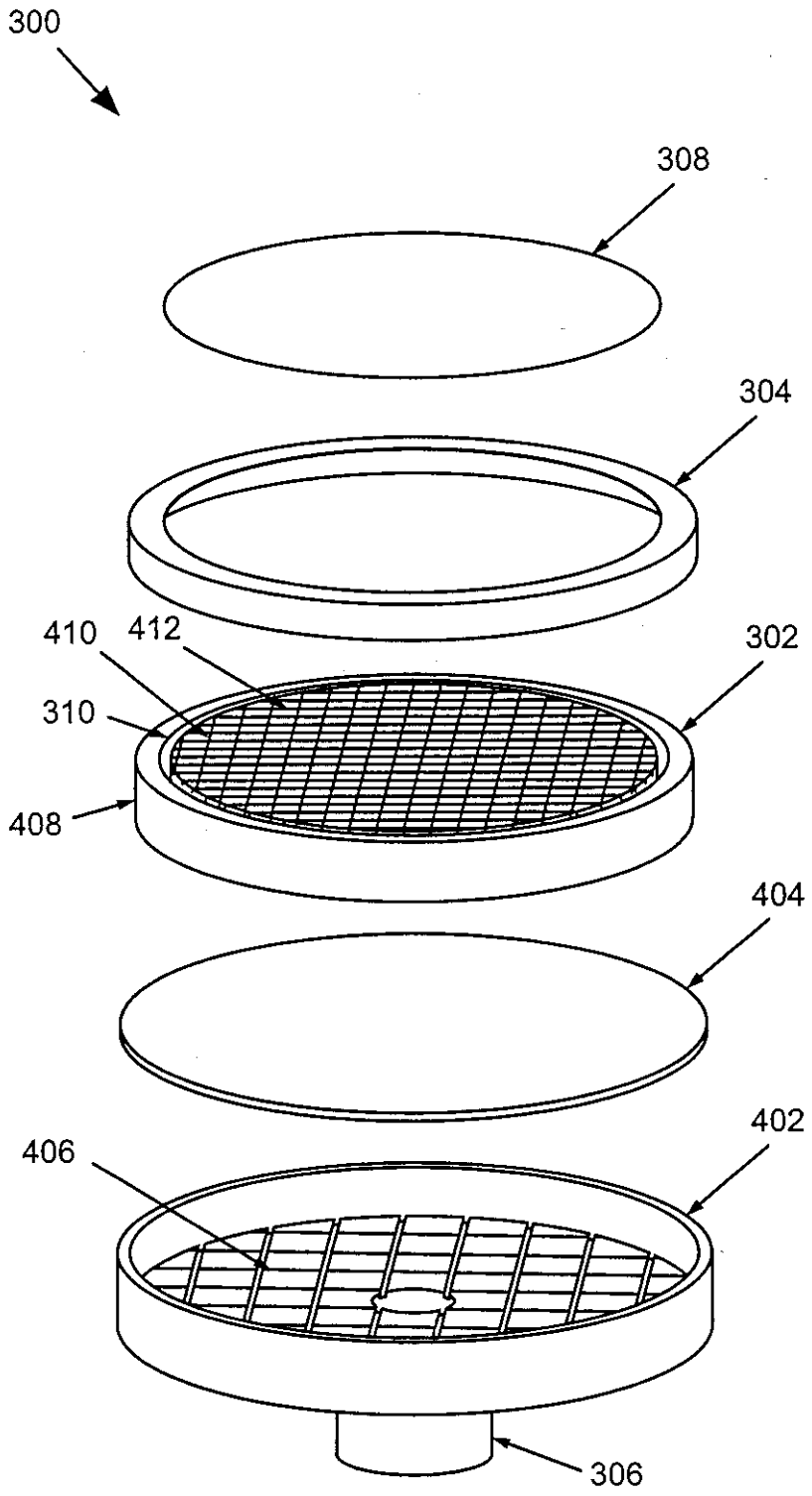



FIG. 4

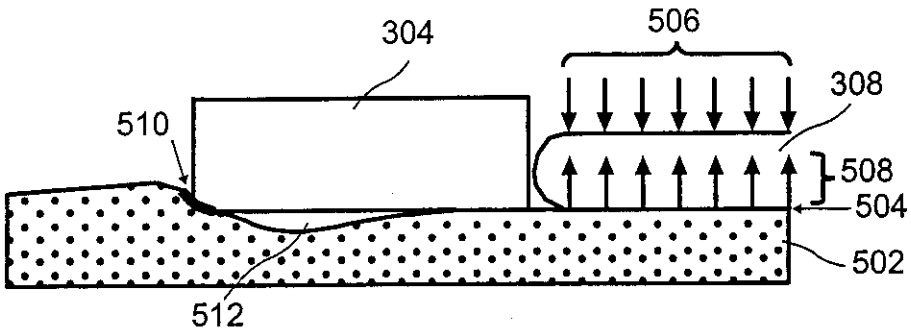



FIG. 5A

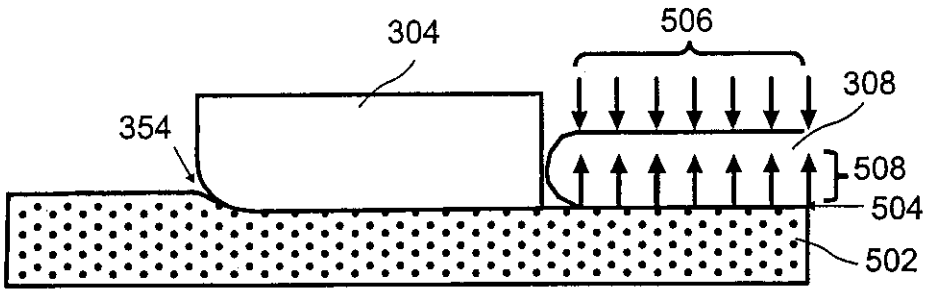



FIG. 5B